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CT1110-W, CT1111-W, CT1112-W, CT1113-W, CT1114-W CT1115-W, CT1116-W, CT1117-W, CT1118-W, CT1119-W DC Input 5-Pin Long Mini-Flat Phototransistor Optocoupler

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Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- Extra low coupling capacitance
- DC input with transistor output
- Operating Temperature range 55 °C to 125 °C
- External creepage distance > 8.0 mm
- Clearance distance >8.4mm
- Distances through insulation > 0.4 mm
- RoHS and REACH Compliance
- Halogen Free Compliance
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5 (VDE0884-5)
 - ✓ CQC GB4943.1, GB8898 (19001231775)
 - ✓ IEC62368 (FI/41119)

Package Outline

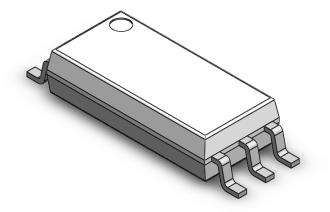
Applications

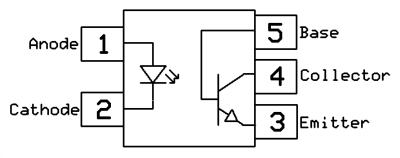
- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Description

The CT111X-W-H series consists of a photo transistor optically coupled to an Infrared-emitting diode in a 5-lead SOP Package.

Schematic







Absolute Maximum Ratings $T_A = 25^{\circ}C$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	5000	VRMS	
Topr	Operating temperature	-55 ~ +125	°C	
Тѕтс	Storage temperature	-55 ~ +150	°C	
Tsol	Soldering temperature	260	°C	
Emitter				
lF	Forward current	50	mA	
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1	А	
VR	Reverse voltage	6	V	
PD	Power dissipation	85	mW	
Detector				
PD	Power dissipation	150	mW	
BVCEO	Collector-Emitter Breakdown Voltage	80	V	
Вусво	Collector-Base Breakdown Voltage	80	V	
BVECO	Emitter-Collector Breakdown Voltage	7	V	
BVEBO	Emitter-Base Breakdown Voltage	7	V	
lc	Collector Current	50	mA	



Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
		IF=10mA	-	1.24	1.4	V	
VF	V _F Forward voltage	IF = 50mA	-	1.45	1.5	V	
IR	Reverse Current	V _R = 6V	-	-	5	μA	
CIN	Input Capacitance	f= 1kHz	-	45	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
BVCEO	Collector-Emitter Breakdown	I _C = 100μA	80	-	-	V	
BVECO	Emitter-Collector Breakdown	I _E = 100μA	7	-	-	V	
Вусво	Collector-Base Breakdown	Ic= 100μA	80	-	-	V	
BVEBO	Emitter-Base Breakdown	I _E = 100μA	7	-	-	V	
I _{CEO}	Collector-Emitter Dark Current	V _{CE} = 20V	-	-	100	nA	
Ісво	Collector-Base Dark Current	V _{CB} = 20V	-	-	20	nA	

Transfer Characteristics

Symbol	Para	meters	Test Conditions	Min	Тур	Max	Units	Notes
		CT1110-W-H		50	-	600		
		CT1115-W-H	-	50	-	150	%	
		CT1116-W-H	IF= 5mA, VCE= 5V	100	-	300		
		CT1117-W-H		80	-	160		
OTD	Current	CT1118-W-H		130	-	260		
CTR	Transfer Ratio	CT1119-W-H		200	-	400		
		CT1111-W-H	– I _F = 10mA, V _{CE} = 5V	60	-	300		
		CT1112-W-H		63	-	125		
		CT1113-W-H		100	-	200		
		CT1114-W-H	-	160	-	320		
Vce(sat)	Collector-Emitte Voltage	r Saturation	IF= 10mA, Ic= 1mA	-	-	0.4	V	
Rio	Isolation Resista	ance	Vio= 500Vdc	5x10 ¹⁰	-	-	Ω	
CIO	Isolation Capaci	tance	f= 1MHz	-	-	1	pF	



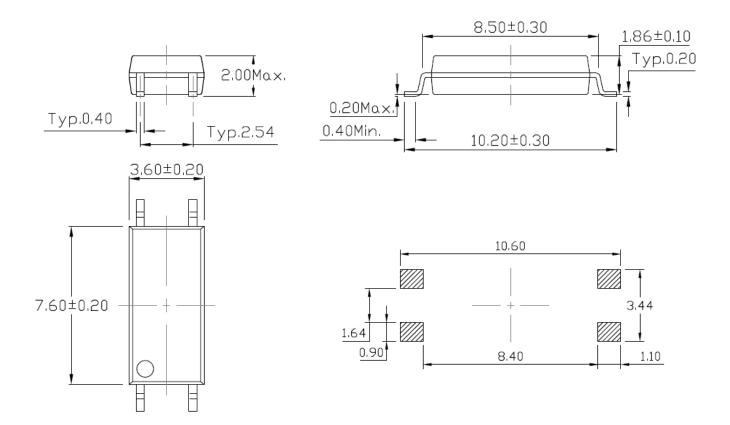
Electrical Characteristics $T_A = 25^{\circ}C$, unless otherwise specified

Switching Characteristics

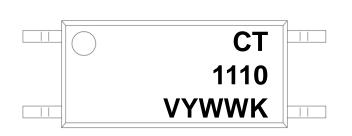
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
Ton	Turn On Time		-	5	-		
Toff	Turn Off Time	- Ic= 5mA, Vcε= 5V, RL= 100Ω -	-	4.2	-		
tr	Rise Time		-	2.8	-	μs	
t _f	Fall Time		-	4.1	-		



Package Dimension Dimensions in mm unless otherwise stated



Marking Information



Note:

- СТ : Denotes "CT Micro"
- 1110 : Part Number
- V : VDE Safety Mark Option (Blank or V)
- : One Digit Year Code Υ
- WW : Two Digit Work Week
- Κ : Manufacturing Code



Ordering Information

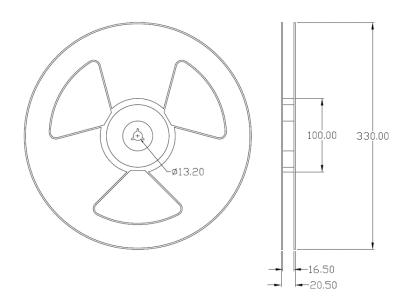
CT111X(V)(Y)-W-H

СТ	= Denotes "CT Micro"
111X	= Part Numbers (X= 0,1,2,3,4,5,6,7,8,9)
V	= VDE Safety Mark Option (Blank or V)
Z	= Tape and Reel Option (T1 or T2)
W	= Outline Color (W, White)
Н	= Lead frame option (H: Iron, None: Copper)

Option	Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Taping	3000Units/Reel
T2	T2 Surface Mount Lead Forming – With Option 2 Taping	

Reel Dimension All dimensions are in mm, unless otherwise stated

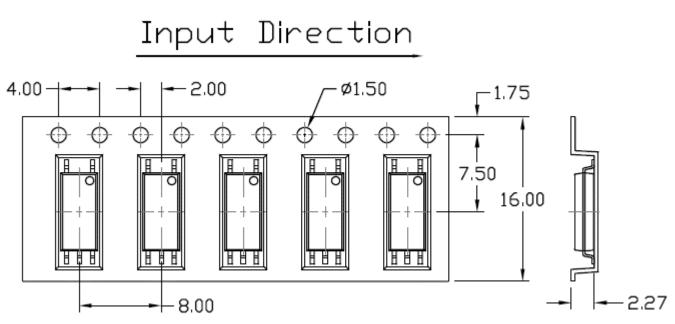
Option T1/T2



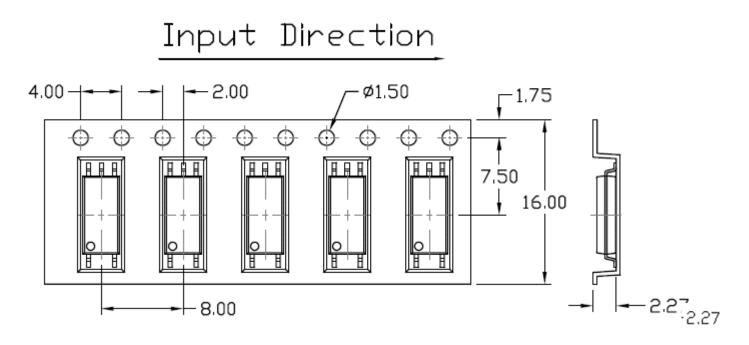


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option T1



Option T2





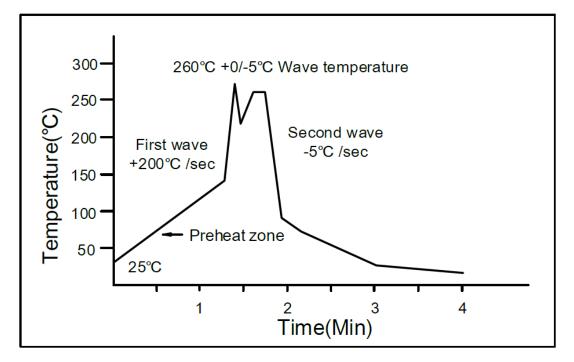
Solderability spec (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (follow the JEDEC standard JESD22-A111)

One time soldering is recommended within the condition of temperature. Temperature: 260+0/-5°C. Time: 10 sec. Preheat temperature:25 to 140°C. Preheat time: 30 to 80 sec.

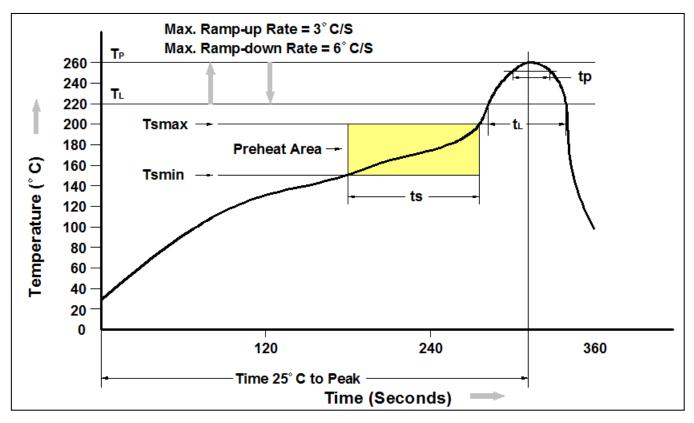


Iron soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process. One time soldering is recommended. Temperature: 350+±10°C Time: 5 sec max.



Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to tթ)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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